

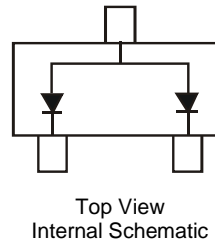
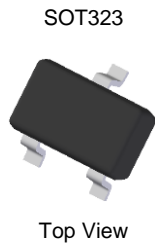
Features

- Fast Switching Speed
- Small Surface-Mount Package
- For General-Purpose Switching Applications
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **The BAW56WQ is suitable for automotive applications requiring specific change control; this part is AEC-Q101 qualified, PPAP capable, and manufactured in IATF 16949 certified facilities.**

<https://www.diodes.com/quality/product-definitions/>

Mechanical Data

- Package: SOT323
- Package Material: Molded Plastic, "Green" Molding Compound; UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish Annealed over Alloy 42 Leadframe (Lead Free Plating) Solderable per MIL-STD-202, Method 208 (e3)
- Polarity: See Diagram
- Weight: 0.006 grams (Approximate)

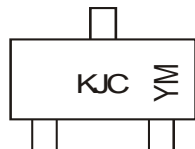


Ordering Information (Notes 4 & 5)

Part Number	Package	Packing	
		Qty.	Carrier
BAW56W-7-F	SOT323	3000	Tape & Reel
BAW56WQ-7-F	SOT323	3000	Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
 2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.
 5. Product manufactured with Date Code 0627 (week 27, 2006) and newer are built with Green Molding Compound. Product manufactured prior to Date Code 0627 are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.

Marking Information



KJC = Product Type Marking Code
 YM = Date Code Marking
 Y = Year (ex: K = 2023); A Bar on Top of the "Y = Year" Denotes AT Site
 M = Month (ex: 5 = May)

Date Code Key

Year	2005	-	2023	2024	2025	2026	2027	2028	2029	2030	2031	2032
Code	S	-	K	L	M	N	P	R	S	T	U	V

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Non-Repetitive Peak Reverse Voltage	V _{RM}	100	V
Peak Repetitive Reverse Voltage	V _{R(RM)}	75	V
Working Peak Reverse Voltage	V _{R(WM)}		
DC Blocking Voltage	V _R		
RMS Reverse Voltage	V _{R(RMS)}	53	V
Forward Continuous Current (Note 6)	I _{FM}	300	mA
Non-Repetitive Peak Forward Surge Current (Note 6)	I _{FSM}	2.0	A
		1.0	

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6)	P _D	200	mW
Thermal Resistance Junction to Ambient Air (Note 6)	R _{θJA}	625	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 7)	V _{(BR)R}	75	—	V	I _R = 2.5μA
Forward Voltage	V _F	—	0.715 0.855 1.0 1.25	V	I _F = 1.0mA I _F = 10mA I _F = 50mA I _F = 150mA
Reverse Current (Note 7)	I _R	—	2.5 50 30 25	μA μA μA nA	V _R = 75V V _R = 75V, T _J = +150°C V _R = 25V, T _J = +150°C V _R = 20V
Total Capacitance	C _T	—	2.0	pF	V _R = 0, f = 1.0MHz
Reverse-Recovery Time	t _{rr}	—	4.0	ns	I _F = I _R = 10mA, I _{rr} = 0.1 × I _R , R _L = 100Ω

Notes: 6. Part mounted on FR-4, 2oz 1inch squared copper pad PC board.
7. Short duration pulse test used to minimize self-heating effect.

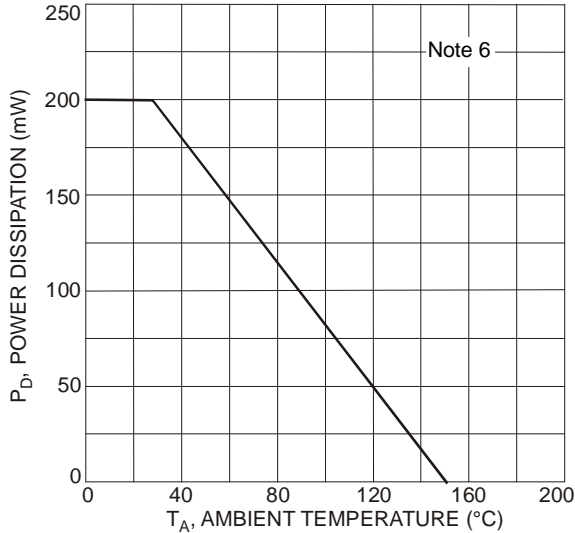


Figure 1. Power Derating Curve, Total Package

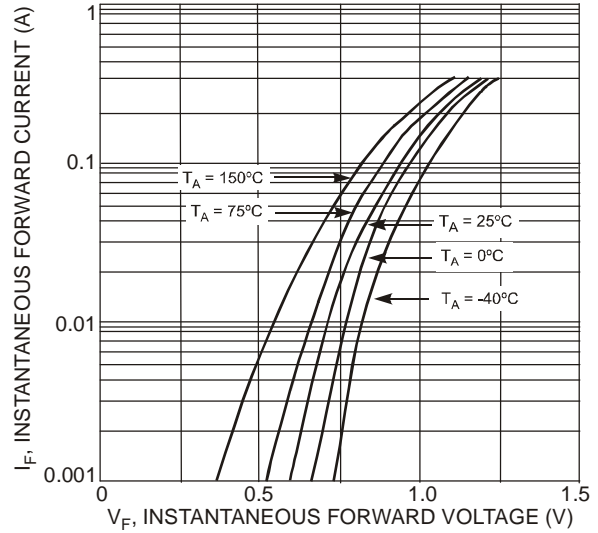


Figure 2. Typical Forward Characteristics, Per Element

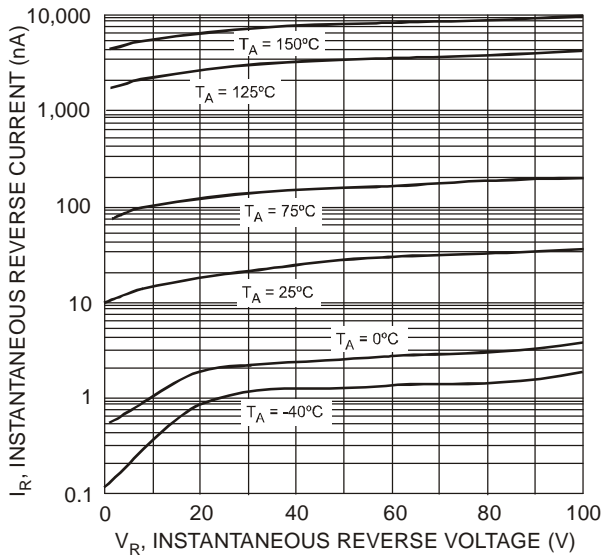


Figure 3. Typical Reverse Characteristics, Per Element

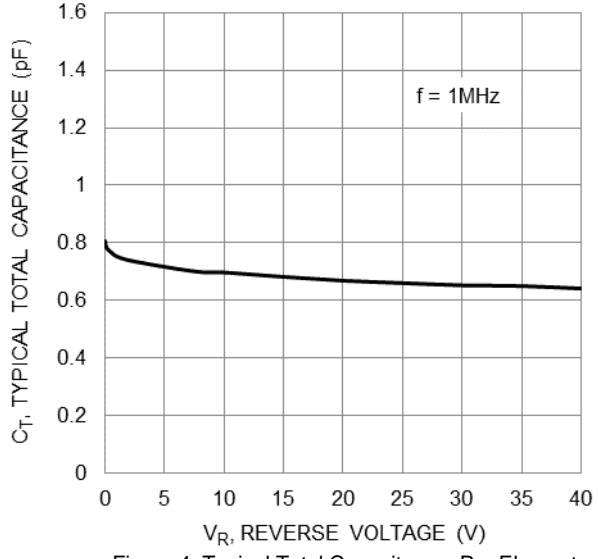


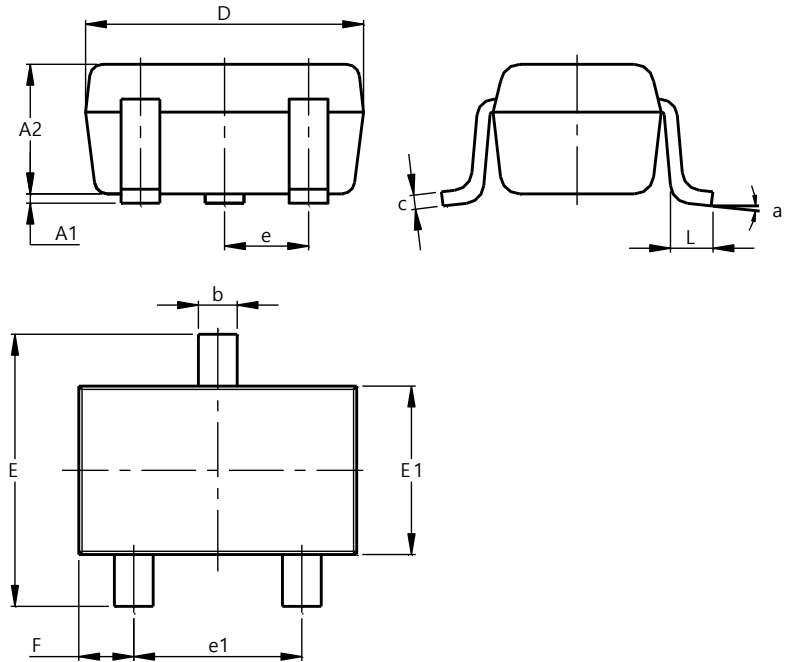
Figure 4. Typical Total Capacitance, Per Element

Note: 6. Part mounted on FR-4, 2oz 1inch squared copper pad PC board.

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT323

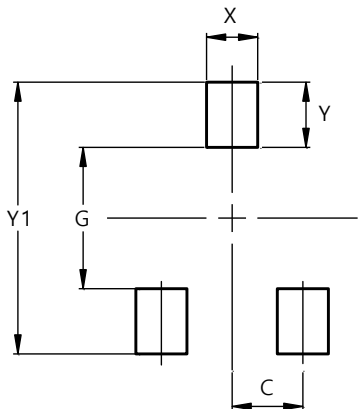


SOT323			
Dim	Min	Max	Typ
A1	0.00	0.10	0.05
A2	0.90	1.00	0.95
b	0.25	0.40	0.30
c	0.10	0.18	0.11
D	1.80	2.20	2.15
E	2.00	2.20	2.10
E1	1.15	1.35	1.30
e	0.650 BSC		
e1	1.20	1.40	1.30
F	0.375	0.475	0.425
L	0.25	0.40	0.30
a	0°	8°	--
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT323



Dimensions	Value (in mm)
C	0.650
G	1.300
X	0.470
Y	0.600
Y1	2.500

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